

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6	(method with fabricating with semiconductor adj device and opening with insulation adj film with interconnection adj layer near3 (copper "Cu") with material near3 opening and concurrently adj spraying near3 nitrogen adj gas with water with liquid adj phase with surface near3 interconnection adj layer near3 opening with nitrogen with dsorbed with surface with interconnection adj laver and water near3 concurrently adj injected with nitrogen adj gaswith carbonated near3 water and ozonized adj water).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/10 16:01
L2	1	(method with fabricating with semiconductor adj device and opening with insulation adj film with interconnection adj layer near3 (copper "Cu") with material near3 opening and concurrently adj spraying near3 nitrogen adj gas with water with liquid adj phase with surface near3 interconnection adj layer near3 opening with nitrogen with asorbed with surface with interconnection adj laver and water near3 concurrently adj injected with nitrogen adj gaswith carbonated near3 water and ozonized adj water).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/10 16:00
S1	194	(copper "cu") near3 (layer film) same (nitrogen with water)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/08 11:11
S2	10	("4503131" "4695775" "4699081" "4985072" "4985076" "5212138" "5648125" "5843517" "5843538" "5910340").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/08 10:46
S3	7	("20020008034" "20020084529" "6022808" "6197181" "6313064" "6486533" "6515368").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/10 15:52

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S5	43	(copper "cu") near3 (layer film) and (nitrogen with water) with (spray\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/08 11:14
S6	2	"6951221"	US-PGPUB; USPAT; USOCR	OR	ON	2007/06/06 19:04
S7	2	09/957652	US-PGPUB; USPAT; USOCR	OR	ON	2007/06/06 19:04
S8	1	10/816958	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/02 18:46